



Intel® Wafer Program

Popular Intel® Components Available in Wafer Form

Overview

- Wafer form factor for reduced size and weight over traditional packaged product
- Wafers proceed through one sort for functional testing prior to customer shipment
- Six-inch wafer form factor for high yield
- Wafers will be available for Intel® embedded microcontrollers, MCS® 51, MCS® 251, MCS® 96 and for the Intel® 186 processor, and the Intel386™ and Intel486™ embedded processors, along with a portion of the Intel® i960® processor family.

Developers can now benefit from lighter designs with reduced costs using Intel® components in wafer form. The Intel® Wafer Program offers six-inch wafers of popular Intel® 8-bit and 16-bit microcontrollers and Intel® embedded processors.

Purchasing in wafers, designers can reduce the size and weight of designs over designs based on traditionally packaged products, while reducing overall system design costs. Wafers allow designers to choose the packaging that best meets their needs and take advantage of emerging packaging technologies for lighter designs — or possibly eliminate the package

altogether in the design. The Intel Wafer Program includes many of Intel's high-yield six-inch wafer products.

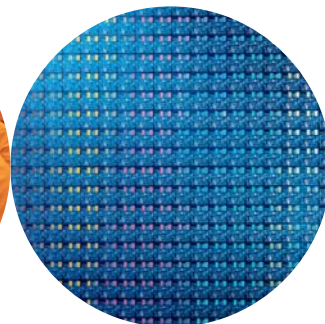
Intel® Wafer Program Components

- Intel® 8-bit microcontrollers:
Intel MCS 51 and Intel MCS 251 family microcontrollers
- Intel® 16-bit microcontrollers:
Intel MCS 96 family microcontrollers
- x86 Intel embedded microprocessors:
Intel® 186/188 processors, Intel386 processors, Intel486 processors
- i960 processors:
CA/CF, KA/KB, SA/SB, MC, JT

Applications

- Industrial power control
- Elevators, thermometers, consumer low-end electronics
- Communications infrastructure equipment and devices

Intel in
Communications



Features

Benefits

Reduced size and weight over the traditionally packaged products	Potentially reduces system weight by 35 percent and the required physical space by 40 percent, enabling smaller, lighter systems
Reduced board size	Lower overall system cost
Higher integration with standard functions	Add only the necessary peripherals without wasting space on unnecessary components
Ability to use the latest in the emerging packaging world	Allows you to package the product to your needs

Intel has been manufacturing these embedded microcontrollers and microprocessors for over a decade and performs a world-class sort process on them. However, since these wafers will be shipped prior to final testing to data sheet specifications at an Intel facility, they will not be offered with the standard packaged product warranty.

Intel Corporation is a member of the Die Products Consortium (DPC). The DPC is a collaborative effort among a set of leading microelectronics companies to progress the widespread use of die products. The DPC is committed to lowering business barriers to the adoption of die products and meet the needs of users for smaller form factor, higher performance, and lower costs. Since the late 1990s the DPC has provided leadership to the IC industry for developing methods that improve die product quality, reliability, handling, shipping and associated infrastructure at the lowest cost. For more information, visit www.dieproduct.com/index.html

Should your design require additional testing levels, please contact your local Intel Authorized Distributor to explore further options.

Intel Access

Developer's Site:	developer.intel.com
Intel® Microcontrollers Home Page:	developer.intel.com/design/embcontrol/index.htm
Intel® Mature Processors Roadmap:	developer.intel.com/design/embcontrol/index.htm
Intel® Technical Documentation Center:	www.intel.com/go/techdoc (800) 548-4725 7 a.m. to 7 p.m. CST (U.S. and Canada) International locations please contact your local sales office.
General Information Hotline:	(800) 628-8686 or (916) 356-3104 5 a.m. to 5 p.m. PST

For more information, visit the Intel Web site at: developer.intel.com

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